



BOARD CHARACTERISTICS

Copper Layer Count:	4	Board Thickness:	1.6062 mm
Board overall dimensions:	51.0540 mm x 45.4914 mm		
Min track/spacing:	0.1500 mm / 0.0000 mm	Min hole diameter:	0.3000 mm
Copper Finish:	None	Impedance Control:	No
Castellated pads:	No	Plated Board Edge:	No
Edge card connectors:	No		

Layer Name	Type	Material	Thickness (mm)	Color	Epsilon R	Loss Tangent
F.Silkscreen	Top Silk Screen	Not specified	0 mm	Not specified	1	0
F.Paste	Top Solder Paste		0 mm		1	0
F.Mask	Top Solder Mask	Not specified	0.01 mm	Not specified	3.3	0
F.Cu	copper		0.035 mm		1	0
Dielectric 1	prepreg	7628	0.2104 mm	FR4 natural	4.4	0
In1.Cu	copper		0.0152 mm		1	0
Dielectric 2	core	7628	1.065 mm	FR4 natural	4.4	0
In2.Cu	copper		0.0152 mm		1	0
Dielectric 3	prepreg	7628	0.2104 mm	FR4 natural	4.4	0
B.Cu	copper		0.035 mm		1	0
B.Mask	Bottom Solder Mask	Not specified	0.01 mm	Not specified	3.3	0
B.Paste	Bottom Solder Paste		0 mm		1	0
B.Silkscreen	Bottom Silk Screen	Not specified	0 mm	Not specified	1	0